

P20 - automatic SMT pick & place machine with optical alignment system



• TECHNICAL DATA

- **PCB**
 - max. placement area 400 x 500mm
- **Components range**
 - from 0402 up to 28 x 28mm
 - Pitch min. 0,4mm
- **Components packing**
 - tapes / sticks / trays
- **Components centering**
 - non-contact alignment
- **Placement rate**
 - up to 1100 cph
- **Feeder capacity**
 - up to 80 x 8mm tapes (automatic+manual) feeder and
 - 2 x (300 x 200mm) - IC-tray with 200 x 300mm PCB size
- **Resolution**
 - X / Y Axis – 0,008mm – linear encoders
 - Z Axis – 0,020mm – linear encoder
 - Rotation – 0,01° – rotation encoder
- **Placement accuracy**
 - +/- 0,03 mm
- **Dimensions and weight**
 - 840 x 630 x 430 mm / ca. 85 kg
- **Supply**
 - 230 V - 50 Hz - 450 W / 0,6 Mpa -20 l/min

• KEY FEATURES

- **precison automatic SMT pick and place machine with optical alignment system**
- **automatic pick & place head**
- **automatic nozzle changer (6 tools)**
- **camerasystem for automatic fiducial**
- **camerasystem for touchless components centering**
- **CAD – editor for pick & place files**
- **teach-in mode**
- **vision inspektion of printing accuracy of solder paste and accuracy of component placement**
- **intelligent feeder system – CAN Bus**
- **operating system: Windows**
- **remote service via internet**
- **Graphical user interface**
- **Application range**
 - prototypes and low volume production
 - pick & place of standard and fine pitch components incl. SOIC, PLCC, BGA, μ BGA, CSP, QFN, SMD LED's